

ABSTRACT

A socket is shown for interconnecting a chip to a printed circuit board, where the socket is comprised of a housing and a substrate. The substrate is of the type comprising a plurality of wire leads extending upwardly from the substrate, and which are interconnected to solder balls on the opposite side of the substrate. The housing has a plurality of slots therethrough, such that the substrate can be positioned on the lower side of the housing with the resilient leads extending upwardly in the slots. A chip receiving face is positioned on the opposite side of the housing for contacting the resilient leads of the substrate. The housing includes resilient arms on opposite sides of the housing, which grip the substrate and which maintain the housing in a resiliently biased position above the substrate, such that the leads remain in their respective slots.

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